



Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 240490US2	SHEET 1 OF 1		SERIAL NO. 10/621,450
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Tsutomu OHISHI, et al.			
				FILING DATE July 18, 2003	GROUP 2622		
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
/Lc/	AA	6,177,957	01/23/2001	E. ANDERSON			
	AB						
	AC						
	AD						
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	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION		
/Lc/	AO	2001-282511	10/12/2001	JAPAN (with English Abstract)	YES	NO	X
/Lc/	AP	2 370 894	07/10/2002	GREAT BRITAIN			
/Lc/	AQ	2 358 070	07/11/2001	GREAT BRITAIN			
/Lc/	AR	2000-194544	07/14/2000	JAPAN (with English Abstract)			X
/Lc/	AS	2 360 163	09/12/2001	GREAT BRITAIN			
	AT						
	AU						
	AV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
	AW						
	AX						
	AY						
	AZ	<input type="checkbox"/> Additional References sheet(s) attached					
Examiner /Lechi Truong/				Date Considered 09/06/2007			
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							



LIST OF RELATED CASES

	<u>Docket Number</u>	<u>Serial or Patent Number</u>	<u>Filing or Issue Date</u>	<u>Patent Appl. Publication No.</u>	<u>Inventor/Applicant</u>
/Lc/	240490US2*	10/621,450	07/18/03	2004/0057067	OHISHI et al.
/Lc/	256489US2	10/900,098	07/28/04		OHISHI et al.

09/06/2007

/Lechi Truong/

*Present Application; listed for information

GJM/sch

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LIST OF RELATED CASES

<u>Docket Number</u>	<u>Serial or Patent Number</u>	<u>Filing or Issue Date</u>	<u>Patent Appl. Publication No.</u>	<u>Inventor/Applicant</u>
/Lc/ 240490US2*	10/621,450	07/18/03	2004/0057067	OHISHI, et al.
/Lc/277754US2	11/216,013	09/01/05		ANDO et al.

09/06/2007

/Lechi Truong/

*Present Application; listed for information

GJM/abd/akh

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		Docket No.: 240490US2	Serial No.: 10/621,450		
LIST OF RELATED CASES CITED BY APPLICANT UNDER 37 CFR 1.56		Inventor: Tsutomu OHISHI, et al.			
		Filing Date: July 18, 2003	Group: 2627		
<u>LIST OF RELATED CASES</u>					
Examiner <u>Initial</u>	<u>Docket No.</u>	<u>Serial or Patent Number</u>	<u>Filing or Issue Date</u>	<u>Patent App. Publication No.</u>	<u>Inventor or Applicant</u>
/Lc/	240490US2*	10/621,450	07/18/03	2004/0057067	OHISHI, et al.
/Lc/	294388US2	11/495,569	07/31/06		OHISHI
/Lc/	294990US2	11/502,516	08/11/06		TANAKA
/Lc/	295540US2	11/509,601	08/25/06		ANDO, et al.
Examiner	/Lechi Truong/		Date Considered	09/06/2007	
<p>*Present Application; listed for information</p> <p>JJK/sch</p> <p>I:\EMEMREL\239s-240s\240490US LIST8.DOC</p>					

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240490US2SERIAL NO.
10/621,450

LIST OF REFERENCES CITED BY APPLICANT

APPLICANT

Tsutomu OHISHI, et al.

FILING DATE

July 18, 2003

GROUP

2622

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
/LC/	AA	5,745,753	04/28/1998	Malcolm MOSHER, Jr.			
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	AL						
	AM						
	AN						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION
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	AQ				
	AR				
	AS				
	AT				
	AU				
	AV				

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

AW	
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AY	
AZ	<input type="checkbox"/> Additional References sheet(s) attached

Examiner /Lechi Truong/

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